

P2010NXE2HFC (Active)

QorIQ, 32-Bit Power Arch SoC, 800MHz, DDR2/3 w/ECC, GbE, PCIe, SRIO, USB, SEC, -40 to 125C, Rev 2.1

[Data Sheet](#)
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Package :
[HBGA689](#)

HBGA689, plastic, thermal enhanced ball grid array; 689 balls; 1 mm pitch; 31 mm x 31 mm x 1.86 mm body

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Operating Characteristics

Parameter	Value
Core Type	e500
Core: Number of cores (SPEC)	1
Operating Frequency [Max (MHz)]	800

Parameter	Value
PCIe	3
External Memory Supported	DDR2 SDRAM, DDR3 SDRAM, SDRAM, SRAM

Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
P2010NXE2HFC (935311284557)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	e2	REACH SVHC	5247.2

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
P2010NXE2HFC (935311284557)	No	3	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)	CCATS	Footprint	Capture Symbol
P2010NXE2HFC (935311284557)	854231	5A002A1	G144297	PDF Cadence Allegro(dra)	PDF Orcad Capture 16.3(olb)

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